

HSB88WA

Silicon Schottky Barrier Diode for High Speed Switching

HITACHI

ADE-208-965 (Z)
Rev.0
Aug. 2000

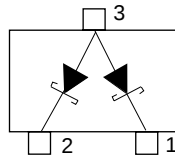
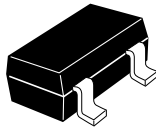
Features

- Low reverse current, Low capacitance.
- CMPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HSB88WA	C7	CMPAK

Pin Arrangement



(Top View)

- 1 Cathode
- 2 Cathode
- 3 Anode

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V_R	10	V
Average rectified current	I_O^*	15	mA
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Note: Per one device.

Electrical Characteristics (Ta = 25°C) *¹

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	0.350	—	0.420	V	$I_F = 1\text{ mA}$
	V_{F2}	0.500	—	0.580		$I_F = 10\text{ mA}$
Reverse current	I_{R1}	—	—	0.2	μA	$V_R = 2\text{ V}$
	I_{R2}	—	—	10		$V_R = 10\text{ V}$
Capacitance	C	—	—	0.80	pF	$V_R = 0\text{ V}$, $f = 1\text{ MHz}$
Capacitance deviation	ΔC	—	—	0.10	pF	$V_R = 0\text{ V}$, $f = 1\text{ MHz}$
Forward voltage deviation	ΔV_F	—	—	10	mV	$I_F = 10\text{ mA}$
ESD-Capability * ²	—	30	—	—	V	C = 200 pF, R = 0 Ω, Both forward and reverse direction 1 pulse.

- Notes: 1. Per one device.
2. Failure criterion ; $I_R > 0.4\text{ }\mu\text{A}$ at $V_R = 2\text{ V}$

Main Characteristic

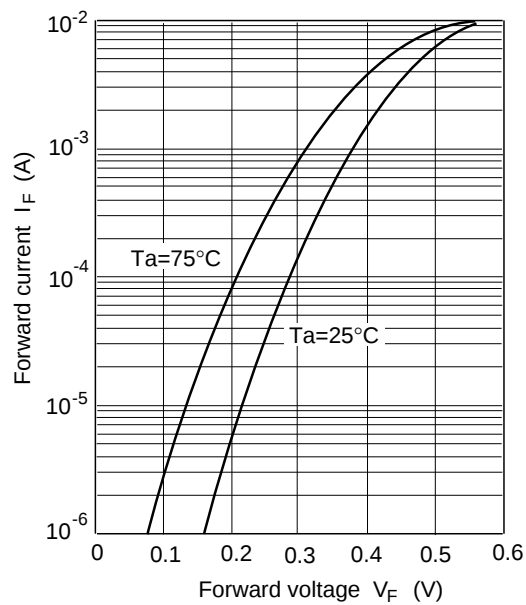


Fig.1 Forward current Vs. Forward voltage

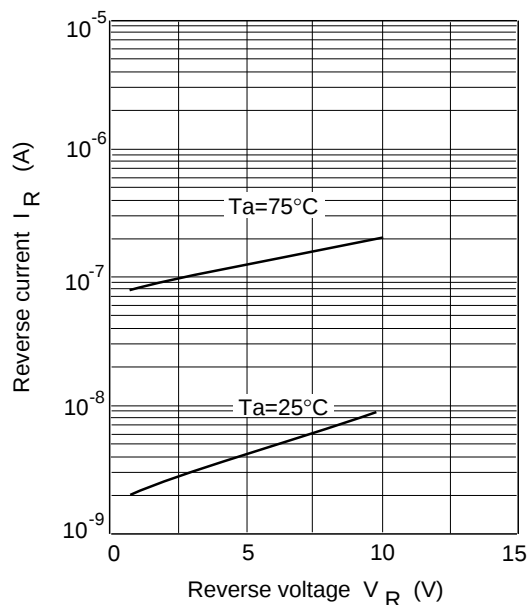


Fig.2 Reverse current Vs. Reverse voltage

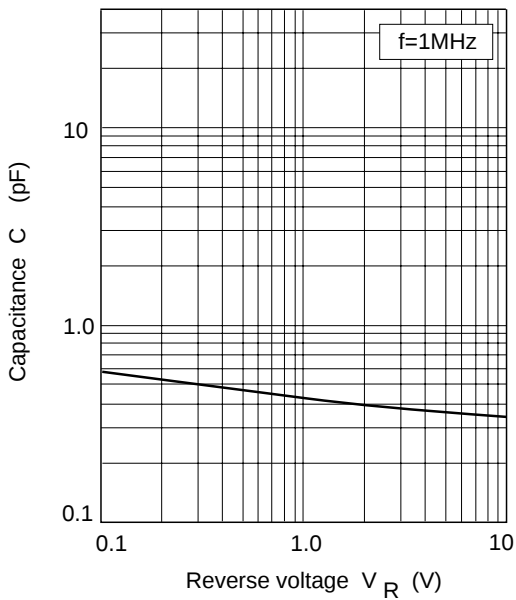


Fig.3 Capacitance Vs. Reverse voltage

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